# Gap Filler 1500 (Two-Part)

Thermally Conductive Liquid Gap Filling Material

#### **Features and Benefits**

- Thermal conductivity: 1.8 W/mK
- Optimized shear thinning characteristics for ease of dispensing
- Excellent slump resistance (stays in place)
- Ultra-conforming with excellent wet-out for low stress interface applications
- 100% solids no cure by-products
- Excellent low and high temperature mechanical and chemical stability



Gap Filler 1500 is a two-part, high performance, thermally conductive liquid gap filling material, which features superior slump resistance and high shear thinning characteristics for optimized consistency and control during dispensing. The mixed system will cure at room temperature and can be accelerated with the addition of heat. Unlike cured thermal pad materials, a liquid approach offers infinite thickness variations with little or no stress to the sensitive components during assembly. Gap Filler 1500 exhibits low level natural tack characteristics and is intended for use in applications where a strong structural bond is not required. As cured, Gap Filler 1500 provides a soft, thermally conductive, form-inplace elastomer that is ideal for fragile assemblies and filling unique and intricate air voids and gaps.

TYPICAL PROPERTIES OF GAP FILLER 1500			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color / Part A	Yellow	Yellow	Visual
Color / Part B	White	White	Visual
Viscosity as Mixed (cps) (1)	250,000	250,000	ASTM D2196
Density (g/cc)	2.7	2.7	ASTM D792
Mix Ratio	1:1	1:1	_
Shelf Life @ 25°C (months)	6	6	_
PROPERTY AS CURED			
Color	Yellow	Yellow	Visual
Hardness (Shore 00) (2)	50	50	ASTM D2240
Heat Capacity (J/g-K)	1.0	1.0	ASTM D1269
Continuous Use Temp (°F) / (°C)	-76 to 347	-60 to 175	_
ELECTRICAL AS CURED			
Dielectric Strength (V/mil)	400	400	ASTM D149
Dielectric Constant (1000 Hz)	6.4	6.4	ASTM D150
Volume Resistivity (Ohm-meter)	1010	1010	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL AS CURED			
Thermal Conductivity (W/m-K)	1.8	1.8	ASTM D5470
CURE SCHEDULE			
Pot Life @ 25°C (min) (3)	60	60	-
Cure @ 25°C (hrs) (4)	5	5	-
Cure @ 100°C (min) (4)	2	2	-
1) Prookfold DV Hali Path Spindla TE @ 20 rpm 25°C			

- 1) Brookfield RV, Heli-Path, Spindle TF @ 20 rpm, 25°C
- 2) Thirty second delay value Shore 00 hardness scale.3) ARES Parallel Plate Rheometer Working life as liquid, time for viscosity to double.
- 4) ARES Parallel Plate Rheometer Estimated time to read 90% cure.

### **Typical Applications Include:**

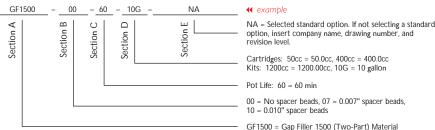
- Automotive electronics
- Computer and peripherals
- Telecommunications
- Thermally conductive vibration dampening
- Between any heat generating semiconductor and a heat sink

## **Configurations Available:**

- Supplied in cartridge or kit form
- With or without glass beads
- Many other special or custom configurations are available upon request

#### **Building a Part Number**

### **Standard Options**



Note: To build a part number, visit our website at www.bergquistcompany.com.

Gap Pad®: U.S. Patent 5,679,457 and others



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